

This listing of claims replaces all prior versions, and listings of claims in the instant application:

Listing of Claims:

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1. (Original) A clamp comprising:
a window formed to expose upward a die mounted on a die pad of a lead frame and leads on an outer circumference of the die on a heater block during a wire bonding process; and
at least one or more observation holes formed in an outer circumference of the window to set a gate of the lead frame within a lead eye box and a lead eye point.
 2. (Original) The clamp as claimed in claim 1, wherein the at least one or more observation holes are located in opposite positions of the outer circumference of the window to detect an orientation not only of a normal lead frame but also of an inverted lead frame.
 3. (Original) A structure comprising:
a substrate comprising an unsymmetrical part; and
a clamp, the unsymmetrical part being visible through an observation hole of the clamp.
 4. (Original) The structure as claimed in claim 3 wherein the unsymmetrical part comprises a gate.
 5. (Original) The structure as claimed in claim 3 wherein the unsymmetrical part comprises a plated layer on a gate.
 6. (Original) The structure as claimed in claim 5 wherein the plated layer comprises a material selected from

the group consisting of aluminum, silver, gold, palladium, nickel, lead, and tin alloys.

7. (Original) The structure as claimed in claim 3 wherein the unsymmetrical part comprises a dent part of a gate.

8. (Original) The structure as claimed in claim 3 wherein the substrate further comprises a support bar.

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9. (Original) The structure as claimed in claim 3 further comprising a camera for setting a lead eye box and a lead eye point on the unsymmetrical part.

10. (Original) The structure as claimed in claim 3 wherein the substrate comprises a normal lead frame.

11. (Original) The structure as claimed in claim 3 wherein the substrate comprises an inverted lead frame.

12. (Original) The structure as claimed in claim 3 wherein the substrate is selected from the group consisting of a lead frame, a printed circuit board, a circuit film, and a circuit tape.

13. (Original) The structure as claimed in claim 3 further comprising a die exposed through a window of the clamp.

14. (Original) The structure as claimed in claim 13 wherein leads of the substrate are exposed through the window of the clamp.

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15. (Original) The structure as claimed in claim 13 wherein the die is a symmetrical die.

16. (Original) The structure as claimed in claim 13 wherein the die comprises a specific pattern.

17-26. (Canceled.)